To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74HC83

4-bit Binary Full Adder (with Fast Carry)

ADE-205-426 (Z)
1st. Edition
Sep. 2000

Description

This improved full adder performs the addition of two 4-bit binary numbers. The sum (Σ) output are provided for each bit and the resultant carry (C_4) is obtained from the fourth bit.

This adder features full internal look ahead across all four bit generating the carry term in ten nanoseconds typically.

This provides the system designer with partial look-ahead performance at the economy and reduced package count of a ripple-carry implementation.

Features

- High Speed Operation: t_{pd} (A_i or B_i to Z_i) = 16 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: V_{CC} = 2 to 6 V
- Low Input Current: 1 μA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μA max (Ta = 25°C)

Function Table

Inputs				Outputs					
				When C_0 = L/When C_2 = L			When C_0 = H/When C_2 = H		
A_1/A_3	B_1/B_3	A_2/A_4	B_2/B_4	$\sum_1/\sum_3$	$\sum_2/\sum_4$	C_2/C_4	$\sum_1/\sum_3$	$\sum_2/\sum_4$	C_2/C_4
L	L	L	L	L	L	L	H	L	L
H	L	L	L	H	L	L	L	H	L
L	H	L	L	H	L	L	L	H	L
H	H	L	L	L	H	L	H	H	L
L	L	H	L	L	H	L	H	H	L
H	L	H	L	H	H	L	L	L	H
L	H	H	L	H	H	L	L	L	H
H	H	H	L	L	L	H	H	L	H
L	L	L	H	L	H	L	H	H	L
H	L	L	H	H	H	L	L	L	H
L	H	L	H	H	H	L	L	L	H
H	H	L	H	L	L	H	H	L	H
L	L	H	H	L	L	H	H	L	H
H	L	H	H	H	L	H	L	H	H
L	H	H	H	H	L	H	L	H	H
H	H	H	H	L	H	H	H	H	H

H : High level

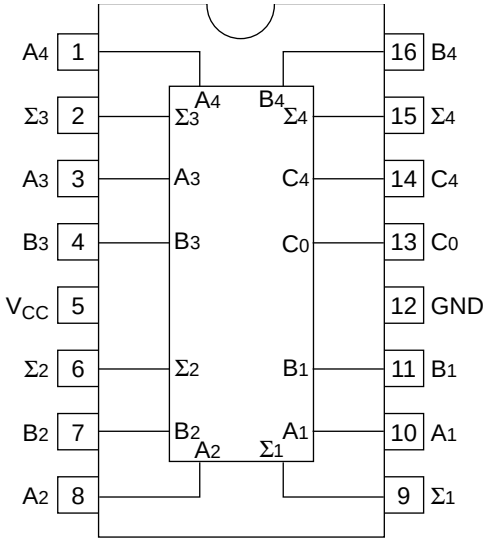
L : Low level

X : Irrelevant

Note: Input conditions at A_1, B_1, A_2, B_2 and C_0 are used to determine outputs $\sum_1$ and $\sum_2$ and the value of the internal carry C_2.

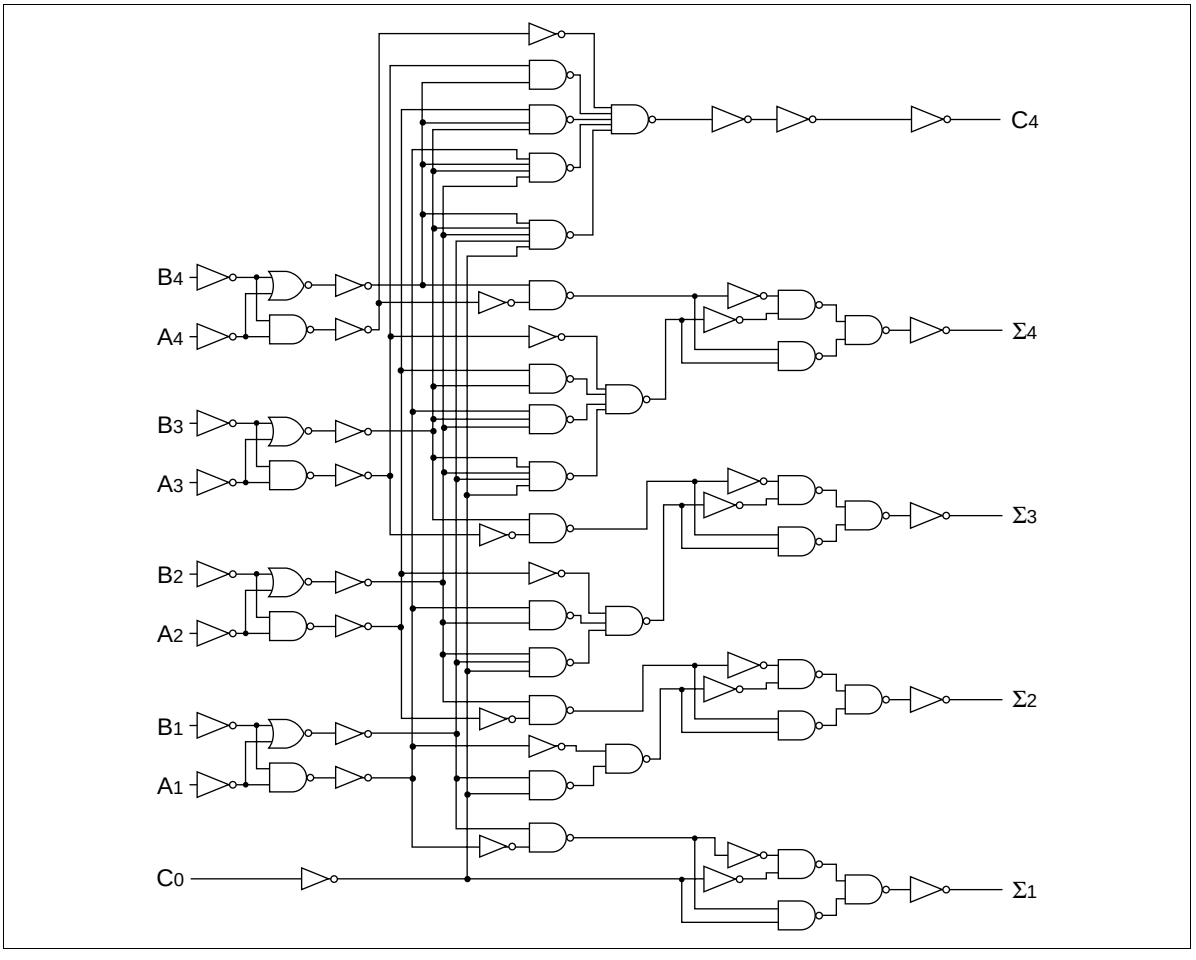
The value at C_2, A_3, B_3, A_4 and B_4 are than used to determine outputs $\sum_3$, $\sum_4$ and C_4

Pin Arrangement



(Top view)

Block Diagram (1//2)



DC Characteristics

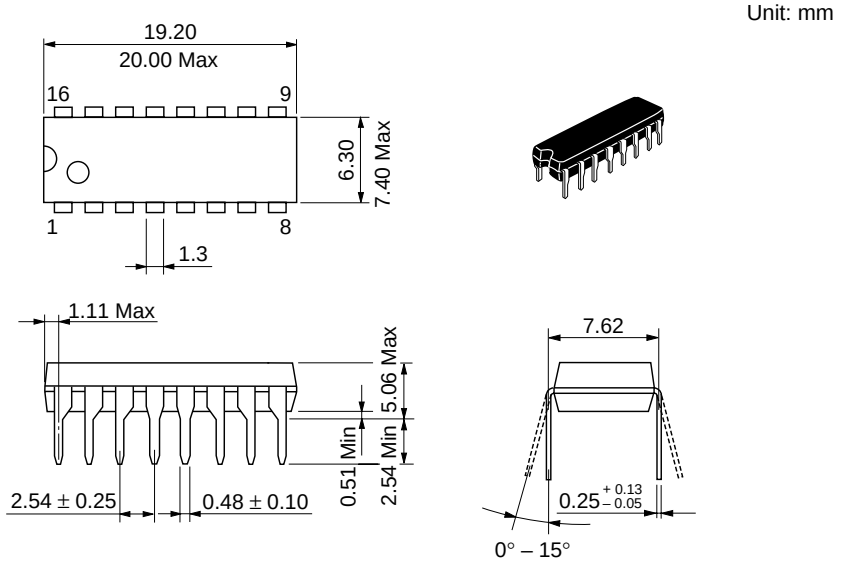
Item	Symbol	V_{CC} (V)	Ta = 25°C Min	Typ	Max	Ta = –40 to +85°C Min	Max	Unit	Test Conditions
Input voltage	V_{IH}	2.0	1.5	—	—	1.5	—	V	
		4.5	3.15	—	—	3.15	—		
		6.0	4.2	—	—	4.2	—		
	V_{IL}	2.0	—	—	0.5	—	0.5	V	
		4.5	—	—	1.35	—	1.35		
		6.0	—	—	1.8	—	1.8		
Output voltage	V_{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V_{IH} or V_{IL} I_{OH} = –20 µA
		4.5	4.4	4.5	—	4.4	—		
		6.0	5.9	6.0	—	5.9	—		
		4.5	4.18	—	—	4.13	—		I_{OH} = –4 mA
		6.0	5.68	—	—	5.63	—		I_{OH} = –5.2 mA
	V_{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V_{IH} or V_{IL} I_{OL} = 20 µA
		4.5	—	0.0	0.1	—	0.1		
		6.0	—	0.0	0.1	—	0.1		
		4.5	—	—	0.26	—	0.33		I_{OL} = 4 mA
		6.0	—	—	0.26	—	0.33		I_{OL} = 5.2 mA
Input current	Iin	6.0	—	—	±0.1	—	±1.0	µA	Vin = V_{CC} or GND
Quiescent supply current	I_{CC}	6.0	—	—	4.0	—	40	µA	Vin = V_{CC} or GND, Iout = 0 µA

AC Characteristics (C_L = 50 pF, Input $t_r = t_f$ = 6 ns)

			Ta = 25°C			Ta = –40 to +85°C			
Item	**Symbol**	**V_{cc} (V)**	**Min**	**Typ**	**Max**	**Min**	**Max**	**Unit**	**Test Conditions**
Propagation delay time	t_{PLH}	2.0	—	—	150	—	190	ns	C_0 to $\sum_i$
	t_{PHL}	4.5	—	19	30	—	38		
		6.0	—	—	26	—	33		
	t_{PLH}	2.0	—	—	150	—	190	ns	A_i or B_i to $\sum_i$
	t_{PHL}	4.5	—	16	30	—	38		
		6.0	—	—	26	—	33		
	t_{PLH}	2.0	—	—	150	—	190	ns	C_0 to C_4
	t_{PHL}	4.5	—	17	30	—	38		
		6.0	—	—	26	—	33		
	t_{PLH}	2.0	—	—	150	—	190	ns	A_i or B_i to C_4
	t_{PHL}	4.5	—	18	30	—	38		
		6.0	—	—	26	—	33		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
	t_{THL}	4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	Cin	—	—	5	10	—	10	pF	

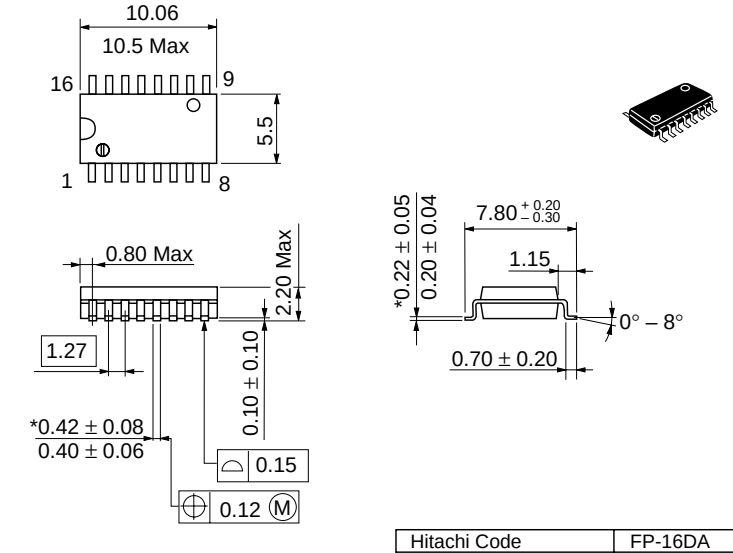
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

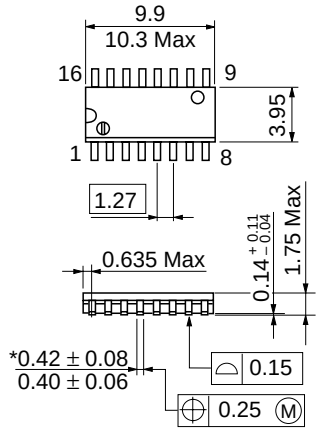
Unit: mm

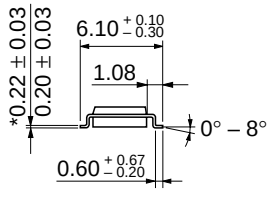


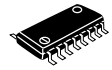
*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

Unit: mm







*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

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